

L Number	Hits	Search Text	DB	Time stamp
1	5	heat adj sink with conductive adj insert	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:07
2	7	(257/720 and 165/104.33).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:09
3	26	(257/720).ccls. and heat adj pipe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:14
4	304	165/104.33.ccls. and thermal adj2 conductivity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:15
5	301	165/104.33.ccls. and thermal adj conductivity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:39
6	13	("5365749"   "5549155"   "5630469"   "5647429"   "5719745"   "5734554"   "5875095"   "6018465"   "6038128"   "6054676"   "6094346"   "6125035"   "6212074").PN.	USPAT	2004/06/01 02:25
7	18	("3586102"   "4563725"   "4833567"   "5126919"   "5168919"   "5296739"   "5323292"   "5430611"   "5508884"   "5713690"   "5754401"   "5829512"   "5831831"   "5863814"   "5880524"   "5880930"   "5932925"   "5945217").PN.	USPAT	2004/06/01 02:26
8	10	("4675783"   "5568360"   "5598320"   "5712762"   "5764482"   "5784256"   "5822187"   "5826645"   "5910883"   "5966286").PN.	USPAT	2004/06/01 02:29
9	2420	heat adj pipe same heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:40
10	816	heat adj pipe same cooling with (IC or chip or component)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/01 02:40